

SOD723

plastic surface mounted package; 2 leads

8 February 2016

Package information

1. Package summary

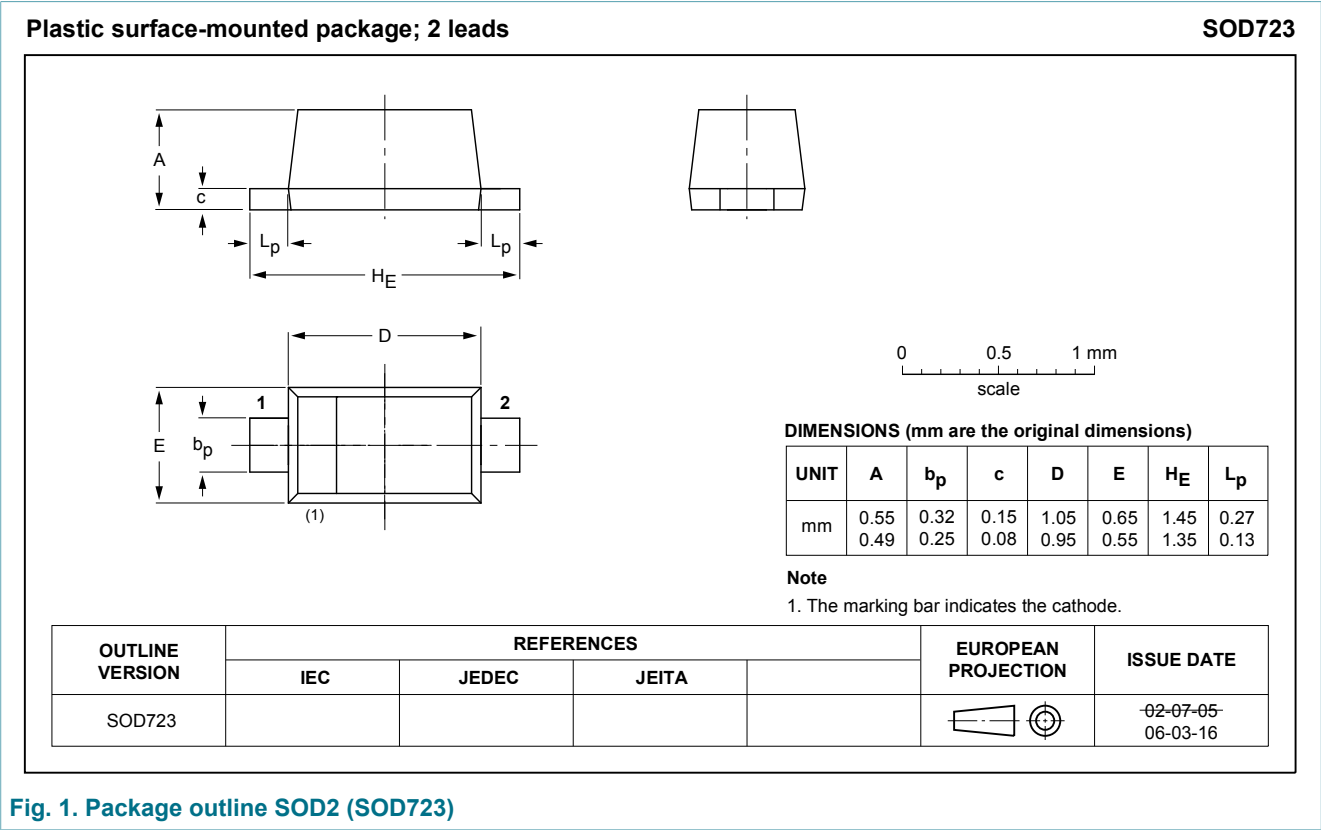
Terminal position code	D (double)
Package type descriptive code	SOD2
Package type industry code	SOD2
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

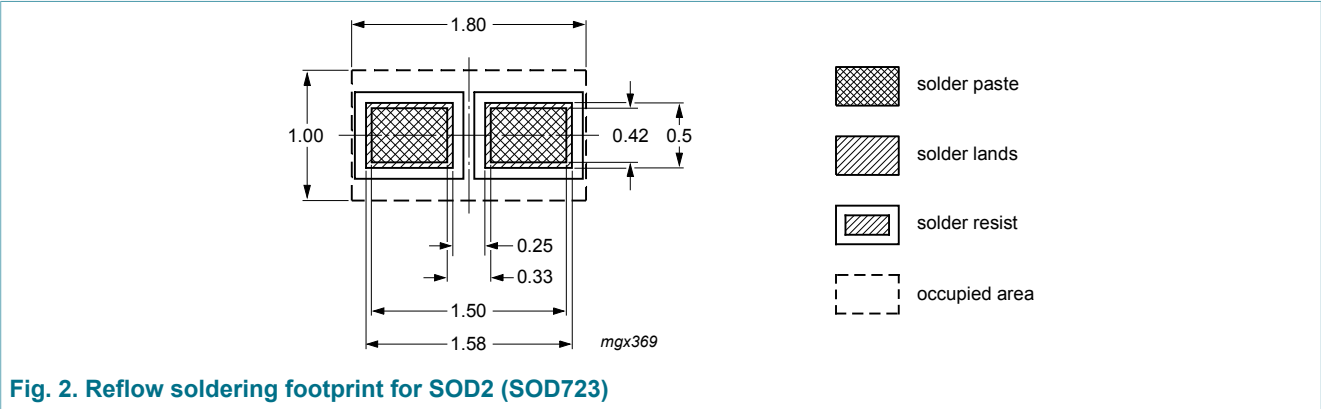
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.95	-	1	1.05	mm
E	package width		0.55	-	0.6	0.65	mm
A	seated height		0.49	-	0.52	0.55	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline



3. Soldering



4. Legal information

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